

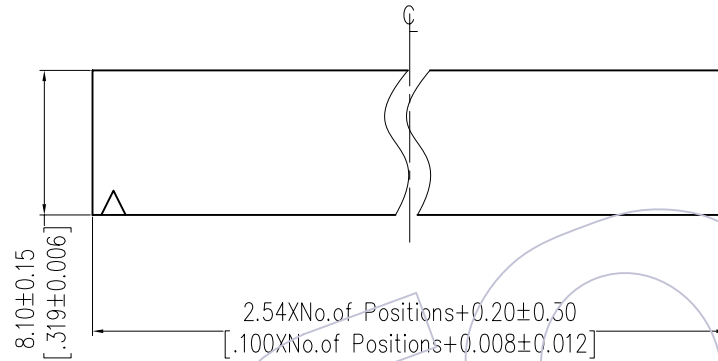
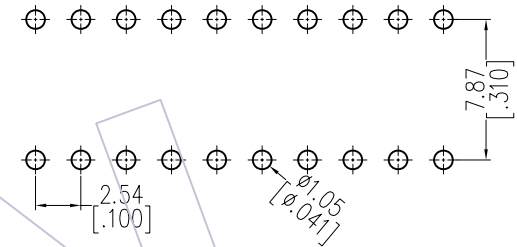
HSF

NOTES:

Current Rating: 3.0AMP
 Contact Resistance: 20mΩ Max
 Withstand Voltage: 1000V AC/DC
 Insulation Resistance: 1000MΩ Min
 Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze
 Contact plating: Au Or Sn over Ni
 Insulator Material: PA9T+30%G.F UL94V-0

Recommended P.C.B Layout(Top Side)
 (PCB BOARD TOLERANCE±0.05)



Ordering Information

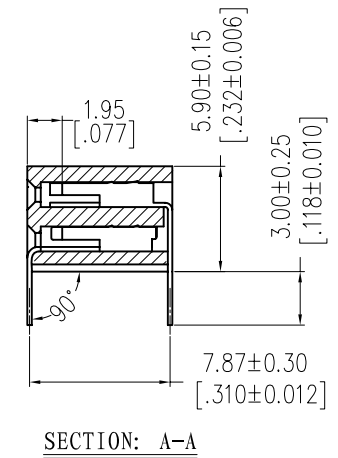
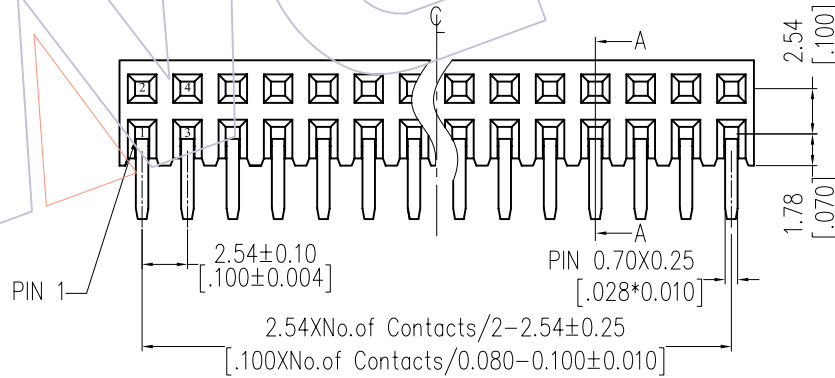
2159 - 2 XX R XX CUN X 1

No. of Pins per ROW: 02-40PIN

Contact Plating:
 G0=Gold Flash
 G3=10μ"Gold
 G4=15μ"Gold
 G5=30μ"Gold
 S0=Gold Flash/Tin
 S3=10μ"Gold/Tin
 S4=15μ"Gold/Tin
 S5=30μ"Gold/Tin
 SN=Tin
 SM=Matte Tin

Packing:
 A=Tray
 T=Tube

Item	Pitch	Mating
Standard	2.54	1125B
Alternate		



REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
				X.X ±0.40	JYHuang	2012/08/24	UNIT	mm	2159-2XXRXXCUNX1
A1	2012/08/24	Change the mating object	-----	X.XX ±0.25	CHECK	DATE	SIZE	A4	
AO	2012/08/10	NEW	-----	X.XXX ±0.15			SHEET	1/1	TITLE: FH2.54mm DUAL ROW 90° DIP H=5.9
				Angle ± 3°	APPROVE	DATE	PROJ.		Customer NO.
				DIM TOL					